



Docket: 740819-405

#14/B
v/a
12/3/02

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of)
Shinichi IMAI) Group Art Unit: 1765
Serial No. 09/630,680) Examiner: A. Shamim
Filed: August 1, 2000)
For: PLASMA PROCESSING METHOD) Date: November 26, 2002

AMENDMENT

Commissioner for Patents
Washington, D.C. 20231
Sir:

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TC 1700 MAIL ROOM

In response to the Examiner's final Office Action mailed August 28, 2002, please consider the following amendments and remarks in connection with Applicant's filing of a Request For Continued Examination filed concurrently herewith in the above-identified application.

IN THE CLAIMS:

Please amend claims 1, 4, 7 and 10 as follows. Claims 1, 4, 7 and 10 are presented below in their amended form. The amendments to the above-noted claims are outlined in an Attachment to the Amendment using the conventional indication method of bracketing and underlining.

B1 62.7 1. (Twice Amended) A plasma processing method comprising the steps of:
placing a substrate inside a reaction chamber of a plasma processing
system, a silicon dioxide film having been formed on the surface of the substrate;